

First	Name	Affiliation	1301	1303	1305	1307	1309	1311	1401	1403
Yaseen	Al-Doori	Southern Methodist Univ.						X		
Jongsup	Baek	LG						X		
Gwen	Barriac	Qualcomm		X	X					
Harry	Bims	Bims Laboratory	X	X	X	X				
Daniel	Borges	Apple						X	X	
Paul	Bottorff	HP							X	
Woo-Jin	Byun	ETRI							X	
George	Calcev	Huawei			X					
Ed	Callawah	Sonristo Micro Devices				X				
Radhakrishna	Canchi	Koyocera				X				
Fill	Carrey	Sony	X	X						
David	Castelow	Airspan		X						
Anthony	Chan	Huawei	X			X		X		
Xin	Chang	Huawei					X			
Paul	Congdon	Tallac Networks					X	X	X	
Subir	Das	Applied Communication Science	X	X	X	X				
Thomas	Derham	Orange		X	X					
Marc	Emmelmann	Fraunhofer Focus		X	X					
Yonggang	Fang	ZTE		X	X	X	X	X	X	X
James	Gilb	Tensorcom							X	
Tim	Godfrey	EPRI	X							
Nada	Golmie	NIST		X						
Daning	Gong	CATR		X						
Steve	Grau	Juniper		X						
Michael	Grigat	DTAG		X						
David	Halasz	Individual		X						
Jeffry	Handal	LSU						X		
Bob	Heile	ZigBee		X						
Ching-Tarng	Hsieh	ITRI	X	X	X	X				
Jen-Yuan	Hsu	ITRI			X					
Brian	Hugino	Taiyo Yaden	X							
Byun Jang	Jeong	ETRI							X	
Seong Soon	Joo	ETRI	X	X						
Hyun Jeong	Kang	Samsung	X							
Hajime	Kanzaki	Hitachi Ltd		X						
John	Kenny	Toyota ITC		X						
Stuart J.	Kerry	OK-BRIT		X						
Farrokh	Khatibi	Qualcomm		X				X		
Per	Kinney	Kinney Consulting	X		X					
Funhide	Kojima	NICT							X	
Jouni	Korhonen	Broadcom							X	
Timo	Koskela	Renesas		X						
Bruce	Kraemer	Marvell				X				
Joe	Kwak	Interdigital			X				X	
Laurent	Lariou	Orange	X							
Jean-Pierre	Le Rouzic	Orange	X	X	X	X				
Hyeong-Ho	Lee	ETRI	X	X		X	X	X		
Zander	Lei	I2R	X							
James	Lepp	Blackberry								X
Josef	Levy	Interdigital	X							
Xingang	Liang	Huawei			X					
Yong	Liu	Apple			X					
Peter	Loc	Huawei	X							
Xiaobo	Long	Goldman Sachs					X			
Scott	Marin	NSN		X	X					
Roger	Marks	EthAirNet Assoc.	X	X	X	X	X	X	X	
Stephen	Mccann	Blackberry	X				X			X
Jordan	Melzer	TELUS	X							

Filip	Mestanov	Ericsson						X		
Fanny	Miinarsky	Octoscope		X						
Jim	Miller	Interdigital		X						
Bob	Miller	AT&T			X					
Apura	Mody	BAE Systems	X							
Michael	Montemurro	Blackberry	X	X	X	X	X	X	X	
Ron	Murizs	Interdigital	X							
Chiu	Ngo	Samsung	X	X	X					
Christian	Niephaus	Fraunhofer				X				
Paul	Nikolich	IEEE 802 chair	X	X						
Yoshihiro	Ohba	Toshiba		X	X	X				
Antonio	Oliva, de la	UC3M				X		X		
Hiro	Onishi	Alpine Electronics							X	
Hyunho	Park	ETRI	X	X		X	X	X		
Xavier Costa	Perez	NEC		X		X				
Charlie	Perkins	Futurewei	X	X	X	X		X		
Lisa	Perry	IEEE SA						X		
Walter	Pienciak	IEEE SA		X	X	X		X		X
Zei	Qin	CATT			X					
Demir	Rakanovic	U-Blox	X	X						X
Harrish	Ramamurthy	Apple			X					
Stephen	Rayment	Ericsson	X		X			X		
Edward	Reuss	Individual		X						
Max	Riegel	NSN	X	X	X	X	X	X	X	X
Dick	Roy	SRA			X	X	X	X	X	
Kazuyuki	Sakoda	Sony		X						
Sam	Sambasivan	AT&T				X	X			
Peter Jeong	Sanykrown	IMRC				X				
Behcet	Sarikaya	Huawei						X	X	X
Ajay	Sigh	Apple			X					
Bo	Sun	ZTE		X						
Jing	Sun	IEEE SA								X
Pat	Thaler	Broadcom							X	
Ian	Timmins	Optical Cable Corporation			X					
Jens	Tingleff	Samsung	X							
Cha-Ling	Tsai	ITRI			X					
Korzuyoshi	Tsukada	Buffalo Inc	X	X						
Prabodh	Varshney	Nokia	X							
Diego	Vincentin	Princeton University						X	X	
Chris	Walhuu	IDCC				X				
Lei	Wang	Interdigital		X	X					
Lisa	Ward	Rodhe & Schwarz	X	X						
Fuiro	Watanabe	Docomo Innovation	X							
Christopher	Williams	Ericsson		X	X	X				
Eric	Wong	Apple	X							X
Harry	Worstell	AT&T		X						
Tao	Xing	Wuxi Sensingnet Institute							X	
Li	Xui	Huawei								X
Akira	Yamada	NTT Docomo	X							
Xun	Yang	Huawei							X	
Sk	Yong	Apple								X
Katsuo	Yunoki	KDDI Research		X						
Nader	Zein	NEC				X				
Guodong	Zhang	Interdigital		X						
Pei Ying	Zhu	Huawei			X					
Yan	Zhuang	Huawei	X					X		
Juan Carlos	Zuniga	Interdigital	X	X	X	X	X	X	X	X